



ALPHA & OMEGA
SEMICONDUCTOR

A06414

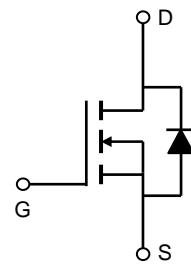
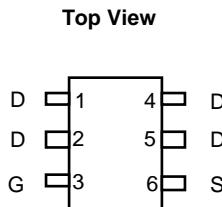
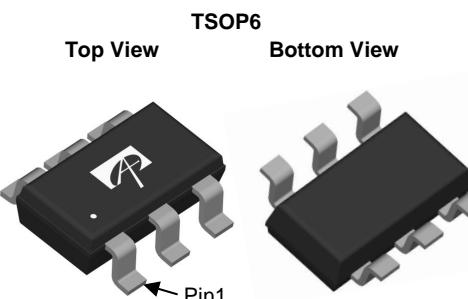
55V N-Channel MOSFET

General Description

The AO6414 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It offers operation over a wide gate drive range from 2.5V to 12V. This device is suitable for use as a load switch.

Product Summary

V_{DS} (V) = 55V
 I_D = 2.4A (V_{GS} = 4.5V)
 $R_{DS(ON)} < 160\text{m}\Omega$ (V_{GS} = 4.5V)
 $R_{DS(ON)} < 200\text{m}\Omega$ (V_{GS} = 2.5V)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	55	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	I_D	2.3	A
$T_A=70^\circ\text{C}$	I_D	1.9	
Pulsed Drain Current ^B	I_{DM}	9	
Power Dissipation ^C	P_D	1.56	W
$T_A=70^\circ\text{C}$	P_D	1.1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	58	80	°C/W
Maximum Junction-to-Ambient ^A		94	120	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	37	50	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=10\text{mA}, V_{GS}=0\text{V}$	55			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=44\text{V}, V_{GS}=0\text{V}$		0.002	1	μA
		$T_J=55^\circ\text{C}$			5	
I_{GSS}	Gate-Source leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.6	1.3	2	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	10			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=2.4\text{A}$		125	160	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		175	210	
V_{SD}	Diode Forward Voltage	$V_{DS}=2.5\text{V}, I_D=1.5\text{A}$		157	200	$\text{m}\Omega$
		$V_{GS}=5\text{V}, I_D=2.4\text{A}$		11		
I_S	Maximum Body-Diode Continuous Current				1.9	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$		214	300	pF
C_{oss}	Output Capacitance			31		pF
C_{rss}	Reverse Transfer Capacitance			12.6		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.3	3	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=25\text{V}, I_D=2.4\text{A}$		2.6	3.3	nC
Q_{gs}	Gate Source Charge			0.6		nC
Q_{gd}	Gate Drain Charge			0.8		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=25\text{V}, R_L=10.4\Omega, R_{\text{GEN}}=3\Omega$		2.3		ns
t_r	Turn-On Rise Time			2.4		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			16.5		ns
t_f	Turn-Off Fall Time			2		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=2.4\text{A}, dI/dt=100\text{A}/\mu\text{s}$		20	30	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=2.4\text{A}, dI/dt=100\text{A}/\mu\text{s}$		17		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

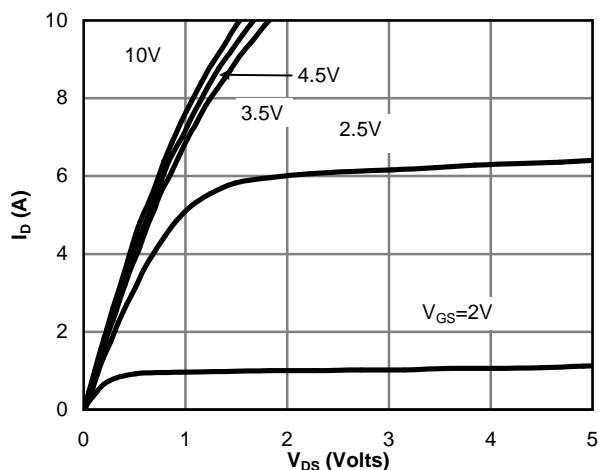


Figure 1: On-Region Characteristics

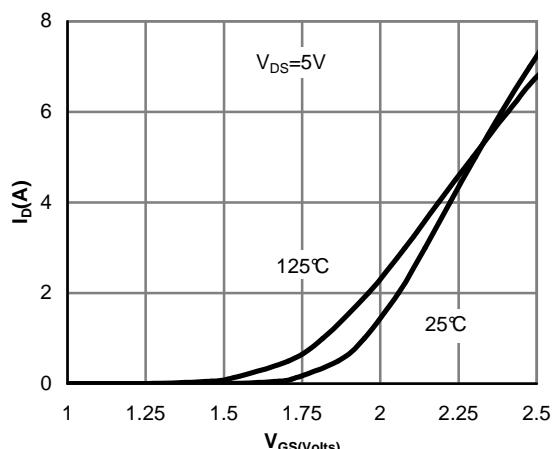


Figure 2: Transfer Characteristics

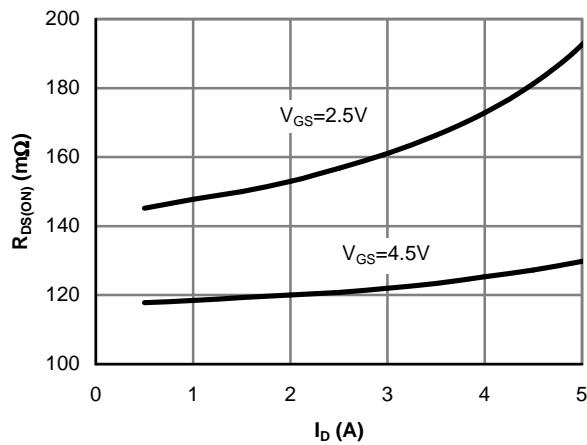


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

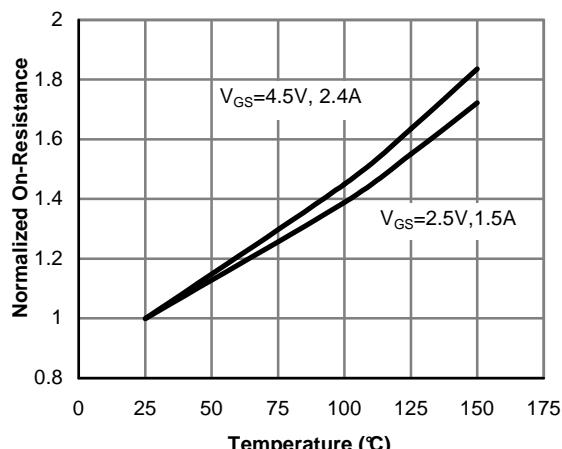


Figure 4: On-Resistance vs. Junction Temperature

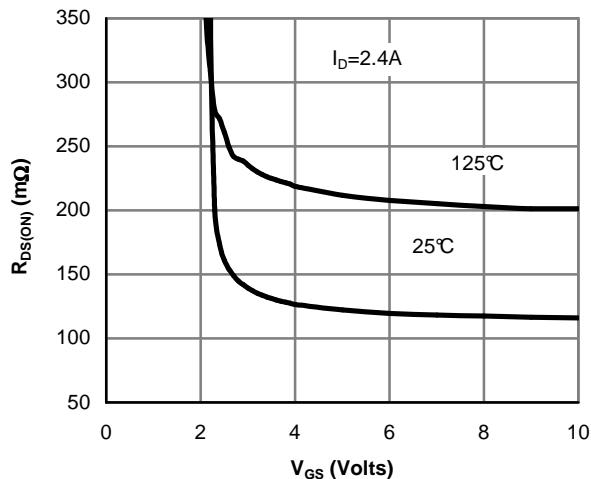


Figure 5: On-Resistance vs. Gate-Source Voltage

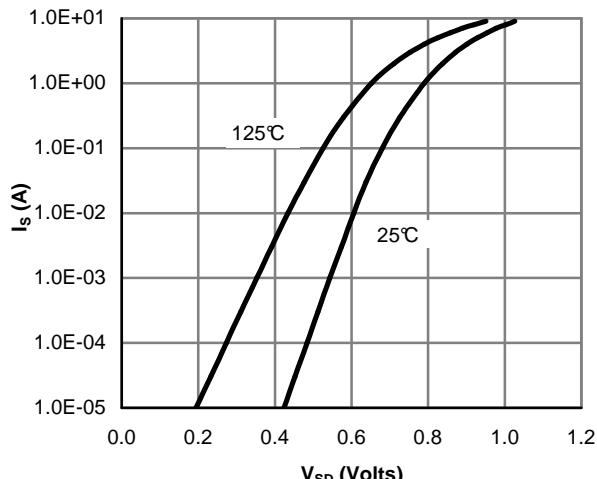


Figure 6: Body-Diode Characteristics

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